

Forced air convection reflow oven Model:BS3010



- Full hot air convection
- 3 Zone control
- PCB width up to 265mm
- Glass Top Design
- Bench-top unit
- Detachable thermocouple

Product Information

(AutoTronik) **BS3010** is a slim size bench-top designed full hot air convection reflow soldering System with microprocessor control which can handle boards up to 265mm width With less than +/-2centigrade degree temperatures gradient.

Glass top Design

Glass top viewing panel allows visual inspection of reflow process.

Bench-top unit

Bench-top unit can be converted to a standalone unit by use of the optional cabinet

Real time temperatures measuring

Detachable thermocouple for measuring substrate temperatures at real time

Microprocessor control

Three heating zones are control by microprocessor with less than +/-2centigrade degree Temperature gradient

Forced air convection reflow oven Modell:BS3010(specifications)

- No shadowing
- Full hot air convection

- No colour sensitivity
- No belt load sensitivity
- No hot spots
- No cold solder joints
- Full visual inspection
- Full microprocessor control
- Full environment friendly
- Full user satisfaction

Process chamber	860mm
Soldering width	265mm
Clearance for assemblies	25mm
Transport system	Stainless steel spring wires conveyor belt
Conveyor speed	10-60cm/min
Soldering temperatures	180-260centigrade degree
Temperature accuracy	+/-2centigrade degree
Number of zones	3
Heatup time	15min
System control	Microprocessor
Power	208/240V.AC
Rated power max	3650 Watts
Dimensions	L X W X H (1540 X 600 X 360)mm
Net weight	60kg
Option	Cabinet